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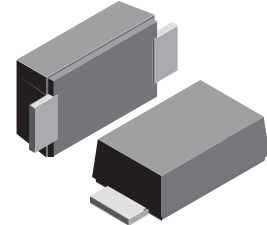
PLED

Product data sheet

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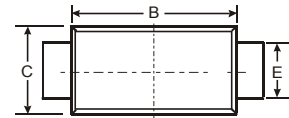
Features

- For surface mounted applications
- Low profile package
- Low incremental surge resistance, excellent clamping capability
- 200W peak pulse power capability with a 10/1000 μ s wave from, repetition rate (duty cycle): 0.01%
- High temperature soldering guaranteed: 260 $^{\circ}$ C/10 seconds, at terminals



Mechanical Data

- Case: JEDEC SOD-123FL, molded plastic over passivated chip
- Polarity: Color band denotes positive end (cathode) except for bidirectional
- Mounting position: Any
- Weight: 0.006 ounces, 0.02 gram



SOD-123FL

Maximum Ratings $T_A = 25^{\circ}$ C unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum P_{PK} Dissipation (PW - 10/1000 μ s)	P_{PK}	200	W
Maximum P_{PK} Dissipation @ $T_a = 25^{\circ}$ C (PW - 8/10 μ s) (Note 2)	P_{PK}	1000	W
DC Power Dissipation @ $T_a = 25^{\circ}$ C (Note 3)	P_D	385	mW
Derate above 25 $^{\circ}$ C		4.0	mW/ $^{\circ}$ C
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\theta JA}$	325	$^{\circ}$ C/W
Thermal Resistance, Junction to Lead (Note 3)	$R_{\theta JL}$	26	$^{\circ}$ C/W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^{\circ}$ C

Notes :

- (1) Non-repetitive current pulse at $T_a = 25^{\circ}$ C, per waveform of Fig. 2.
- (2) Non-repetitive current pulse at $T_a = 25^{\circ}$ C, per waveform of Fig. 5.
- (3) Mounted with recommended minimum pad size, DC board FR4.

TYPE	Marking	Reverse Stand-Off voltage	Breakdown Voltage Min. @ I_T	Breakdown Voltage Max. @ I_T	Test Current	Reverse Leakage @ V_{RWM}	Maximum Clamping Voltage @ I_{PP}	Peak Pulse Current
		V_{RWM} (V)	$V_{BR MIN}$ (V)	$V_{BR MAX}$ (V)	I_T (mA)	I_R (μ A)	V_C (V)	I_{PP} (mA)
PDCV300JB-MS	JK	30	33.3	36.8	1.0	1.0	48.4	4.1

FIG.1 - PULSE DERATING CURVE

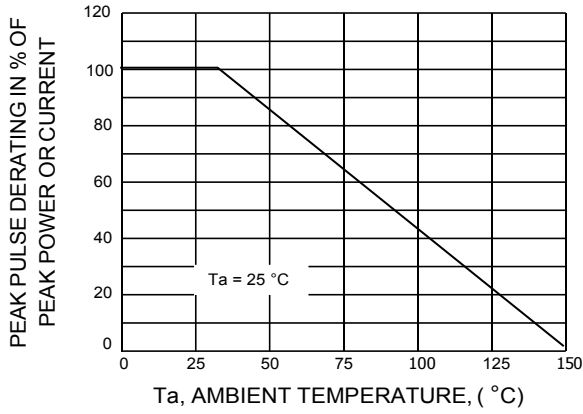


FIG.2 - 10 x 1000 μs PULSE WAVEFORM

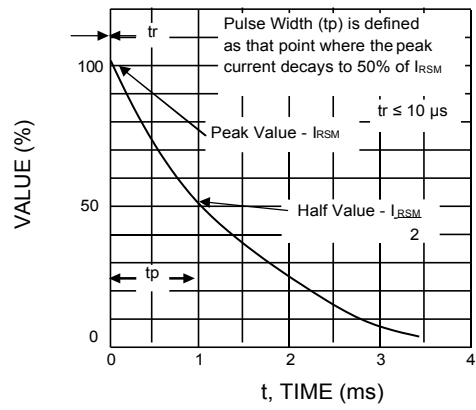


FIG.3 - STEADY STATE POWER DERATING

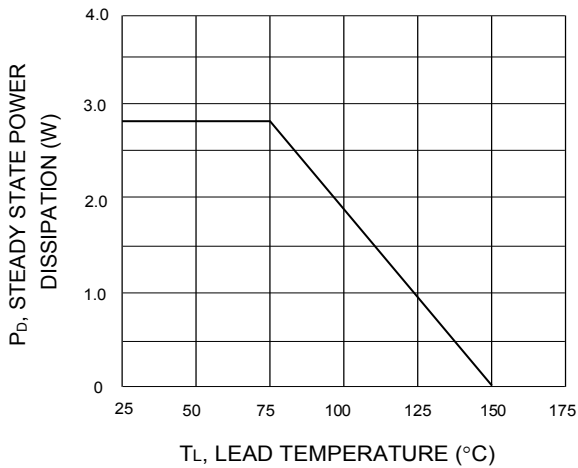


FIG.4 - PULSE RATING CURVE

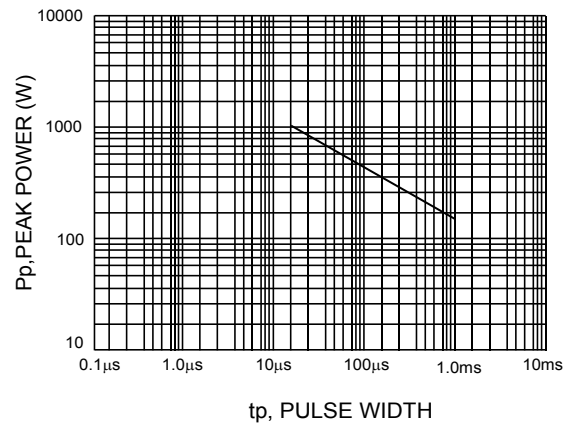


FIG.5 - 8 x 20 μs PULSE WAVEFORM

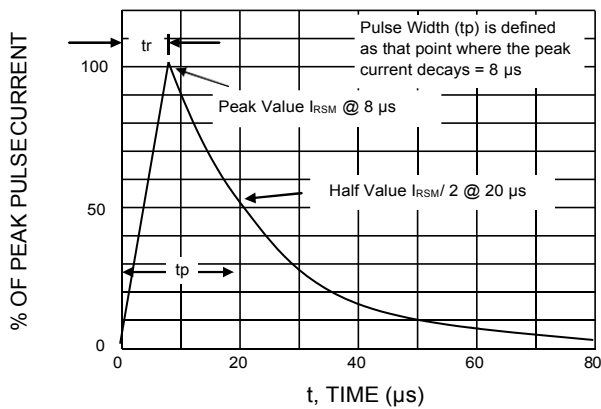
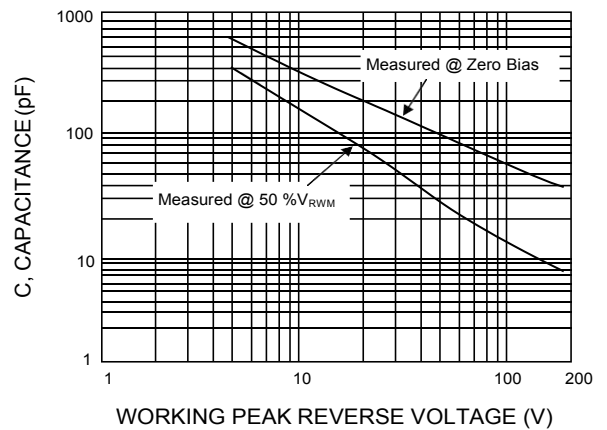
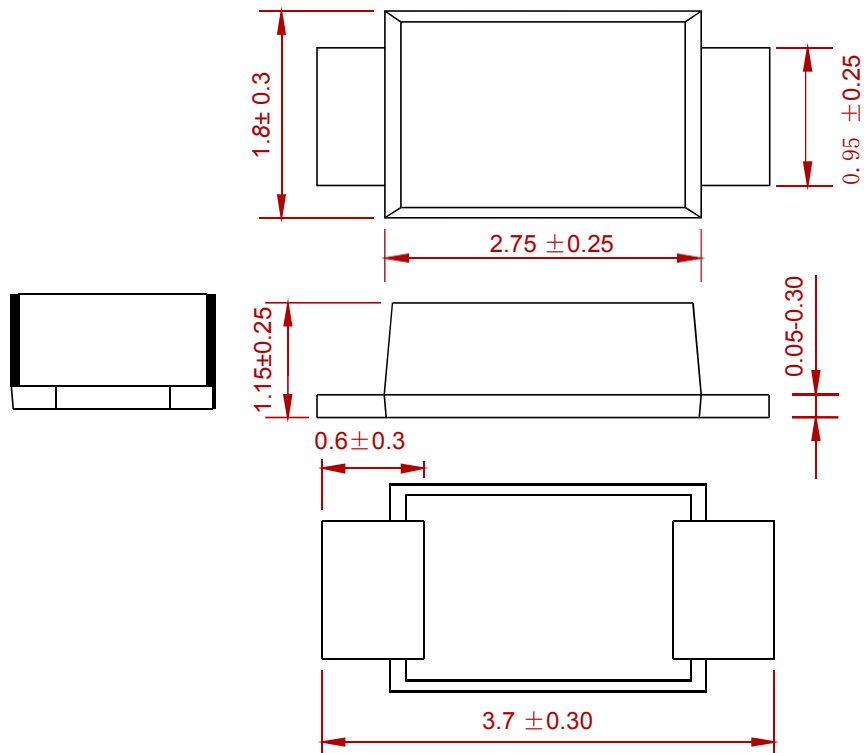


FIG.6 - CAPACITANCE VS. WORKING PEAK REVERSE VOLTAGE

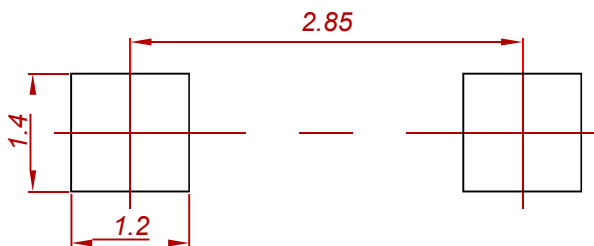


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PDCV300JB-MS	SOD-123FL	3000

单击下面可查看定价，库存，交付和生命周期等信息

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